TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (MACH II π -MOS V)

TPCS8007-H

High-Speed Switching Applications Switching Regulator Applications DC/DC Converter Applications

- Low drain-source ON-resistance: RDS (ON) = 0.36Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 2.1 \text{ S (typ.)}$
- Low leakage current: $IDSS = 100 \mu A (max) (VDS = 200 V)$
- Enhancement model: $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Character	istic	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	200	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V_{DGR}	200	V	
Gate-source voltage		V _{GSS}	±20	V	
	DC (Note 1)	I _D	1.9	Α	
Drain current	Pulse (Note 1)	I _{DP}	7.6	A	
Drain power dissipation	n (t = 10 s) (Note 2a)	PD	1.5	W	
Drain power dissipation (t = 10 s) (Note 2b)		PD	0.6	VV	
Single-pulse avalanche energy(Note3)		E _{AS}	2.3	mJ	
Avalanche current		I _{AR}	1.9	Α	
Repetitive avalanche energy (Note2a, Note 4)		E _{AR}	0.15	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

Unit: mm

(0.525)

1.2.3. Source
4 Gate
5.6.7.8 Drain

JEDEC

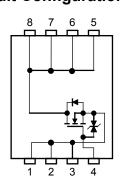
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2-3R1F

Weight: 0.036 g (typ.)

Circuit Configuration



Note: For Notes 1 to 4, refer to the next page.

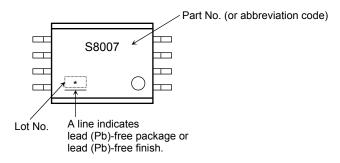
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Handle with care.

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R _{th (ch-a)}	83.3	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R _{th (ch-a)}	208	°C/W

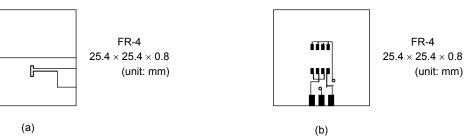
Marking (Note 5)



Note 1: The channel temperature should not exceed 150°C during use.

Note 2:

a) Device mounted on a glass-epoxy board (a)



2

b)

Device mounted on a glass-epoxy board (b)

Note 3: V_{DD} = 50 V, T_{ch} = 25°C (initial), L = 1.0 mH, R_G = 25 Ω , I_{AR} = 1.9 A

Note 4: Repetitive rating: pulse width limited by maximum channel temperature

Note 5: O on the lower right of the marking indicates Pin 1.

* Weekly code: (Three digits)

Week of manufacture

(01 for first week of year, continuing up to 52 or 53)

Year of manufacture

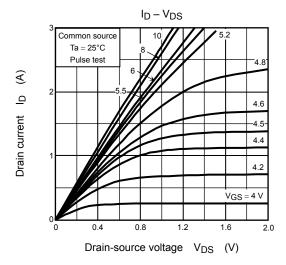
(The last digit of the calendar year)

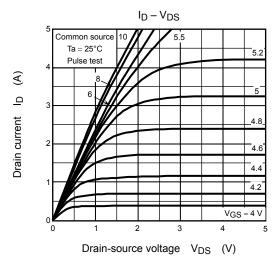
Electrical Characteristics (Ta = 25°C)

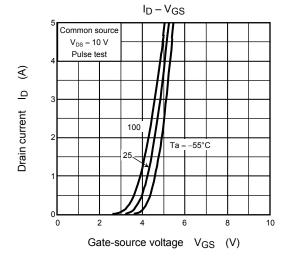
Ch	aracteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cutoff curre	nt	I _{DSS}	V _{DS} = 200 V, V _{GS} = 0 V	_	_	100	μА
		V _{(BR)DSS}	$I_D = 10$ mA, $V_{GS} = 0$ V	200	_	_	
Drain-source brea	akdown voltage	V _{(BR)DSX}	$I_D = 10 \text{ mA}, V_{GS} = -5 \text{ V}$ $I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	200	_	_	٧
		V _{(BR)DSX}		150	_		
Gate threshold vo	oltage	V _{th}	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$	2.0	_	4.0	V
Drain-source ON-	-resistance	R _{DS (ON)}	$V_{GS} = 10 \text{ V}, I_D = 0.9 \text{ A}$		0.36	0.45	Ω
Forward transfer	admittance	Y _{fs}	$V_{DS} = 10 \text{ V}, I_D = 0.9 \text{ A}$	0.9	2.1		S
Input capacitance		C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		600		pF
Reverse transfer capacitance		C _{rss}			20		pF
Output capacitance		Coss			220		pF
Switching time	Rise time	t _r	ACS 0 A D = 0.00 A A D = 0.00 A A D = 0.00 A	_	35	_	
	Turn-on time	t _{on}		_	95	_	200
	Fall time	t _f		_	20	_	ns
	Turn-off time	t _{off}	Duty \leq 1%, $t_W = 10 \mu s$	_	120	_	
Total gate charge (gate-source plus	otal gate charge gate-source plus gate-drain) Qg		$V_{DD} \simeq 160 \text{V}, V_{GS} = 10 \text{ V},$ $I_{D} = 1.9 \text{ A}$	_	10	_	nC
Gate-source charge		Q _{gs}		_	7.5	_	nC
Gate-drain ("Miller") charge		Q _{gd}	ון – ו.פא	_	2.5	_	nC
Gate switch charge		Q _{sw}		_	3.3		nC

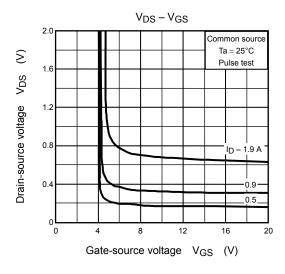
Source-Drain Ratings and Characteristics (Ta = 25°C)

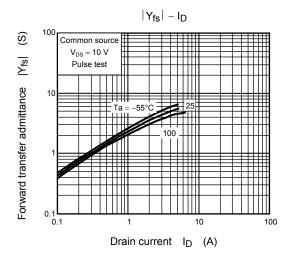
Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current (pulse)	(Note 1)	I _{DRP}	_	_	_	7.6	Α
Forward voltage (diode)		V_{DSF}	$I_{DR} = 1.9 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-2.0	V

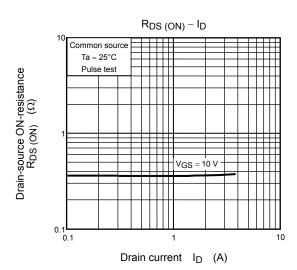


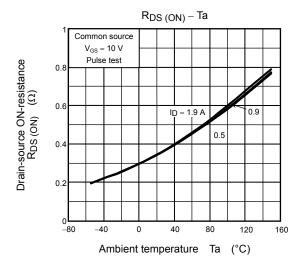


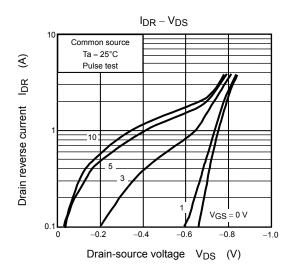


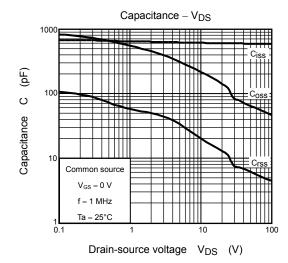


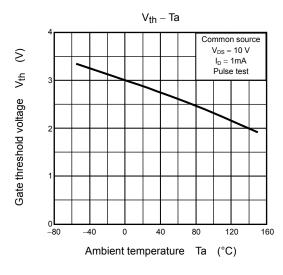


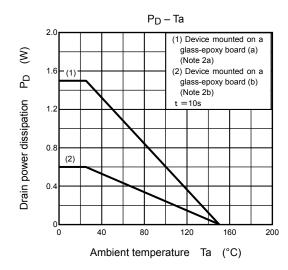


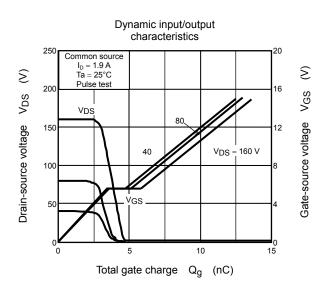




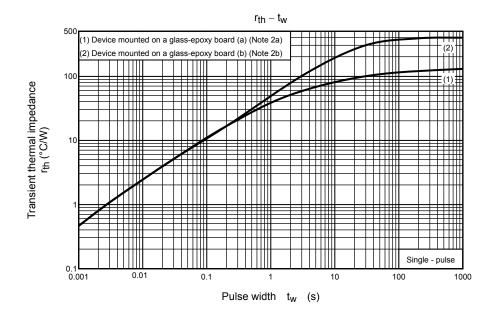


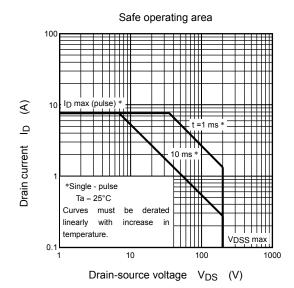






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